



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260903003.1	PCN Issued	September 04, 2026
Qualification of an alternate mount compound material for select devices		Sample request deadline:	October 04, 2026
		Estimated 1st ship date:	November 03, 2026
Sample requests received after October 04, 2026 will not be supported.			

Change type(s)
Assembly Material

PCN Details

Description of Change:		
This PCN is to inform of an alternate Mount Compound material set for the list of devices in the product affected sections below. The current mount compound (die attach material) used in the manufacturing of your product is being discontinued by our supplier and will reach end-of-life. To maintain uninterrupted supply of your product, we are requesting your review and approval no later than November 03, 2026 to help avoid any disruption to production continuity on your end.		
What	Current	Proposed
Mount Compound	4204053	4208458
Qual details are provided in the Qual Data Section.		
Reason for Change:	Continuity of supply	

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Request the Supporting Data Packet (SDP) for more details on the changes.								
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table><tr><td>RoHS</td><td>REACH</td><td>Green Status</td><td>IEC 62474</td></tr><tr><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td></tr></table>	RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change
RoHS	REACH	Green Status	IEC 62474						
☒ No Change	☒ No Change	☒ No Change	☒ No Change						
Changes to product identification resulting from this PCN:	None								

Products Affected:			
TMS320C6713BPYP200	TMS32C6713BPYPA167	TMS32C6713BPYPA200	

Qualification Report

Approve Date 09-July-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TMS32C6713BPYPYA200	QBS Package Reference: S1508017C1PLNR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device TMS32C6713BPYPYA200 is qualified at MSL4 260C
3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site:

TI Qualification ID: R-CHG-2404-008

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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